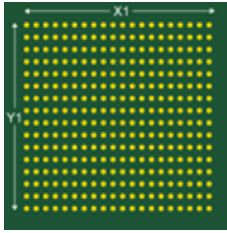


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<b>Part Number/ Rev</b>	<b>: amINO/ 1.0</b>
<b>PCB Size in X</b>	<b>: 0.51 inches X 0.59 inches</b>
<b>Outer Layer</b>	<b>: Signal</b>
<b>BGA Pitch</b>	<b>: 0.65 mm</b>
<b>Total Number of Pins</b>	<b>: 49</b>
<b>BGA Pins Pattern</b>	<b>: X1 = 7 Pins Y1 = 7 Pins</b>

Cost Index

1 2 3 4 5 6 7 8 9 10

2.4

0.0005

Layer	Impedance Model	Impedance (ohms)	Trace Width (mils)	Space (mils)
Layer 1	Soldermask Coated Microstrip Single-ended	51.7	5	--
Layer 1	Soldermask Coated Microstrip Differential Pair	90.03	5	6
Layer 3	Stripline Single-ended	51.04	4	--

Number of Layers	Number of Signal Layers	Number of Sequential Laminations	Number of Plane Layers	Maximum Number of Laser Drills	Mechanical Drills
6	4	1	2	4	2

BGA Fan out Recommendations

BGA Area Trace Geometry

	Trace/Space within BGA area	Maximum number of Traces between adjacent BGA pads/vias
Top Layer	5 mils	0
Inner Layers	5 mils	0
Bottom Layer	5 mils	0

BGA Area Detail

MicroVia Pad Diameter	: 13.5 mils
MicroVia Drill Diameter	: 7 mils
Mechanical MicroVia Pad Diameter	: 16 mils
Mechanical MicroVia Drill Diameter	: 8 mils

Outside of BGA Area

MicroVia Pad Diameter	: 13.5 mils
MicroVia Drill Diameter	: 7 mils
Mechanical MicroVia Pad Diameter	: 16 mils
Mechanical MicroVia Drill Diameter	: 8 mils

Via Set Information

This stack up supports the following via set

L1-L2	L1-L3	L1-L5	L1-L6
L2-L3	L2-L5	L2-L6	
L4-L5	L4-L6		
L5-L6			